





# **Model Curriculum**

**QP Name: Package Design Engineer (Semiconductor)** 

QP Code: ELE/Q0123

QP Version: 3.0

NSQF Level: 5

**Model Curriculum Version: 3.0** 

Electronics Sector Skills Council of India || 155, 2nd Floor, ESC House, Okhla Industrial Area - Phase 3, New Delhi – 110020





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## **Training Parameters**

Sector	Electronics
Sub-Sector	Semiconductor & Components
Occupation	Product Design - S&C
Country	India
NSQF Level	5
Aligned to NCO/ISCO/ISIC Code	NCO-2015/3118.0302
Minimum Educational Qualification and Experience	Completed 2nd year of UG (UG Diploma) (Physics/ Electronics/ Electrical/Mechanical) with 1.5 years of Relevant Experience OR Completed 3 year diploma after 10th (Electronics/Electrical/ Mechanical) with 3 Years of Relevant Experience OR Previous relevant Qualification of NSQF Level (4.5) with 1.5 years of Relevant Experience #Relevant Experience in Semiconductor & Components.
Pre-Requisite License or Training	NA
Minimum Job Entry Age	18 Years
Last Reviewed On	01.05.2025
Next Review Date	31.10.2025
NSQC Approval Date	08.05.2025
QP Version	3.0
Model Curriculum Creation Date	01.05.2025
Model Curriculum Valid Up to Date	31.10.2025
Model Curriculum Version	3.0
Minimum Duration of the Course	570 Hours
Maximum Duration of the Course	570 Hours





## **Program Overview**

This section summarizes the end objectives of the program along with its duration.

#### **Training Outcomes**

At the end of the program, the learner should have acquired the listed knowledge and skills:

- Describe the process of Semiconductor Manufacturing, Assembly, Testing & Packaging evaluating customer requirements and issues.
- Demonstrate the evaluation process of customer requirements and semiconductors processing.
- Demonstrate the uses of all standards related to Package Designing
- Demonstrate the process of Implementation of all Quality Standards with Documentation
- Demonstrate various practices to be followed to maintain health and safety at work.

#### **Compulsory Modules**

The table lists the modules and their duration corresponding to the Compulsory NOS of the QP.

NOS and Module Details	Theory Duration	Practical Duration	On-the-Job Training Duration (Mandatory)	On-the-Job Training Duration (Recommended)	Total Duration
ELE/N0156: Package Design	66:00	54:00	30:00	00:00	150:00
Module 1: Package Designing	66:00	54:00	30:00	00:00	150:00
ELE/N0157: Electrical Simulation	30:00	60:00	30:00	00:00	120:00
Module 2: Electrical Simulation	30:00	60:00	30:00	00:00	120:00
ELE/N0158: Thermal Simulation	30:00	30:00	60:00	00:00	120:00
Module 3: Thermal Simulation	30:00	30:00	60:00	00:00	120:00
ELE/N0159: Mechanical Simulation	30:00	30:00	60:00	00:00	120:00
Module 4: Mechanical Simulation	30:00	30:00	60:00	00:00	120:00

#### 4 | Package Design Engineer (Semiconductor)





DGT/VSQ/N0102: Employability Skills (60 Hours)	24:00	36:00	00:00	00:00	60:00
Module 5: Employability	24:00	36:00	00:00	00:00	60:00
Skills (60 Hours)					
Total Duration	180:00	210:00	180:00	00:00	570:00





## **Module Details**

## Module 1: Package Designing

Mapped to ELE/N0156

#### **Terminal Outcomes:**

• State the role and responsibilities of Package Designing

Duration: 66:00	Duration: 54:00		
Theory – Key Learning Outcomes	Practical – Key Learning Outcomes		
<ul> <li>Sketch rough package as per specification.</li> <li>Feasibility study and characterization methods to optimize best design</li> <li>understanding of material, package dimensions, package structures, semiconductors etc.</li> </ul>	<ul> <li>functionalities such as layer, location, bending angles, thickness, layer thickness etc</li> <li>Based on netlist create wire bond diagram</li> <li>Optimize substrate wirebond PAD's dimensions</li> </ul>		
<ul> <li>Understanding of output pins and their electrical characteristics</li> <li>Create netlist using above schematic</li> </ul>	<ul> <li>Create multiple metal layers as per customer requirements</li> <li>understanding of SMD and NSMD types of substrate</li> </ul>		
Optimize for best Dimensions (Vias, Core Material, Solder Mask etc)			
Classroom Aids			
Training Kit - Trainer guide, Presentations, White	eboard, Marker, projector, laptop		
Tools, Equipment and Other Requirements			
NA			





### Module 2: Electrical Simulation Mapped to ELE/N0157

#### **Terminal Outcomes:**

- Describe the process of standard implementations for Electrical Simulation Process
- Demonstrate the process of verification all Parameters

Duration: 30:00	Duration: 60:00			
Theory – Key Learning Outcomes	Practical – Key Learning Outcomes			
<ul> <li>Understanding of fabrication processes</li> <li>Through Knowledge of JEDEC Standards.</li> </ul>	<ul> <li>8D Reports, Statistical Tools JMP etc, DMAC, APQP, 7S etc</li> <li>Demonstrate the use of relevant PPE such as an ESD wrist strap to protect</li> </ul>			
<ul> <li>understanding of material properties (Electrical Behavior) of device and</li> </ul>	from Electrostatic Discharge (ESD) and other electrical hazards.			
<ul> <li>Package</li> <li>How to Get quality Certifications</li> </ul>	• How to observe & create Signal integrity, RLC Parameters and Eye Diagrams			
<ul> <li>findout best leg based on DOE and verify it by releasing bigger sample size</li> </ul>	•			
<ul> <li>understanding of Signal integrity</li> </ul>				
Classroom Aids				
Training kit (Trainer guide, Presentations). Whiteboard, Marker, projector, laptop				
Tools, Equipment and Other Requirements				
Electrical Simulation Tools				





### Module 3: Thermal Simulation Mapped to ELE/N0158

- Describe the process of Thermal Simulation.
- Demonstrate the process of Thermal Simulation
- Demonstrate the process of cost and Productivity Improvement

Duration: 30:00	Duration: 30:00			
Theory – Key Learning Outcomes	Practical – Key Learning Outcomes			
<ul> <li>Understanding of melting point, CTE, TG, Curing Temperature etc.</li> <li>Find out best leg based on DOE and verify it by releasing bigger sample size</li> <li>Describe the process of Cost and productivity Improvement</li> <li>understanding of All materials thermal Characteristics</li> <li>Describe the design of Experiments (DOE) Expertise</li> <li>Description on Understanding of working principal of machines to improve UPH</li> </ul>	<ul> <li>Demonstrate the use of relevant tools and equipment for the Die Attach Process.</li> <li>Demonstrate the use of relevant PPE such as an ESD wrist strap to protect from Electrostatic Discharge (ESD) and other electrical hazards.</li> <li>How to observe &amp; create Signal integrity, RLC Parameters and Eye Diagrams</li> <li>Find out early-stage thermal issues</li> </ul>			
Classroom Aids				
Training kit (Trainer guide, Presentations). White	board, Marker, projector, laptop			
Tools, Equipment and Other Requirements				
Thermal Simulation Tools				





### Module 4: Mechanical Simulation Mapped to ELE/N0159

#### **Terminal Outcomes:**

• Knowledge about all tools and equipment's useful for Mechanical Simulation

Duration: 30:00	Duration: 30:00		
Theory – Key Learning Outcomes	Practical – Key Learning Outcomes		
<ul> <li>Good understanding of material properties (Mechanical Behavior) of device and package</li> <li>understanding of All materials Mechanical Characteristics</li> <li>Understanding of melting point, CTE, TG, Curing Temperature etc.</li> <li>best leg based on DOE and verify it by releasing bigger sample size</li> <li>Understanding of physical verification tool as such as Mechanical testers (To measure tensile strength, breaking strength etc. )</li> <li>Thermal Shock related to tool Operation and process set up</li> </ul>	<ul> <li>Understanding of Interaction of Die/Device with package material</li> <li>Expert in Mechanical simulation tool</li> <li>Warpage Measurement (Shad moiré etc) related to tool Operation and process set up</li> <li>understanding of material strength and its behavior with temperature and humidity</li> <li>How to observe &amp; create mechanical simulation diagram</li> </ul>		
Classroom Aids			
Training kit (Trainer guide, Presentations)			
Tools, Equipment and Other Requirements			
Equipment's related to Mechanical Simulation			





### Module 5: Employability Skills (60 Hours) Mapped to DGT/VSQ/N0102

#### **Terminal Outcomes:**

- Discuss about Employability Skills in meeting the job requirements
- Describe opportunities as an entrepreneur.
- Describe ways of preparing for apprenticeship & Jobs appropriately.

Duration: 24:00	Duration: 36:00
Theory – Key Learning Outcomes	Practical – Key Learning Outcomes
<ul> <li>Explain constitutional values, civic rights, responsibility towards society to become a responsible citizen</li> </ul>	<ul> <li>List different learning and employability related GOI and private portals and their usage</li> </ul>
• Discuss 21 <sup>st</sup> century skills	• Show how to practice different
<ul> <li>Explain use of basic English phrases and sentences.</li> </ul>	environmentally sustainable practices.
<ul> <li>Demonstrate how to communicate in a well-behaved manner</li> </ul>	<ul> <li>Exhibit 21st century skills like Self- Awareness, Behavior Skills, time management, etc.</li> </ul>
<ul> <li>Demonstrate how to work with others</li> </ul>	<ul> <li>Show how to use basic English sentences for everyday conversation</li> </ul>
<ul> <li>Demonstrate how to operate digital devices</li> </ul>	in different contexts, in person and over the telephone
<ul> <li>Discuss the significance of Internet and Computer/ Laptops</li> </ul>	<ul> <li>Demonstrate how to communicate in a well</li> <li>-mannered way with others.</li> </ul>
<ul> <li>Discuss the need for identifying business opportunities</li> </ul>	<ul> <li>Demonstrate how to communicate effectively using verbal and nonverbal</li> </ul>
• Discuss about types of customers.	communication etiquette
• Discuss on creation of biodata	Utilize virtual collaboration tools to     work offectively
<ul> <li>Discuss about apprenticeship and opportunities related to it.</li> </ul>	<ul> <li>work effectively</li> <li>Demonstrate how to maintain hygiene and dressing appropriately.</li> </ul>
	Perform a mock interview
Classroom Aids	

#### Tools, Equipment and Other Requirements

Computer, UPS, Scanner, Computer Tables, LCD Projector, Computer Chairs, White Board

OR

Computer Lab





### Module 6: On-the-Job Training Mapped to Package Design Engineer (Semiconductor)

IVId	ndatory Duration: 180:00	Recommended Duration: 00:00			
Location: On Site					
Ter	minal Outcomes				
1.	Explain the functions of a Package Design.				
2.	List the preliminary tasks involved in the repa	ir and maintenance of a tools and its peripherals			
3.	Demonstrate how to perform preliminary che	ecks on a computer and its peripherals.			
4.	Perform steps to inspect the Package Designi	ng to identify defective modules/ components.			
5.	Perform repair and maintenance activities as	per the Service Level Agreement (SLA).			
6.	Perform steps to test the functioning of Mach	nineries after repair.			
7.	Communicate product and service-related in	formation to the customer.			
8.	8. Employ appropriate practices to interact and coordinate with supervisor and colleagues.				
•••					
9.					





## Annexure

## **Trainer Requirements**

Trainer Prerequisites						
Minimum Educational	Specialization	Relevant Industry Experience		Traini	ng Experience	Remarks
Qualification		Years	Specialization	Years	Specialization	
Diploma/ Degree/ ITI/ Certified in relevant CITS Trade	(Electrical/Electronics / Mechanical)	2	Electronic Designing	1	Electronics	

Trainer Certification			
Domain Certification	Platform Certification		
"Package Design Engineer (Semiconductor)	Recommended that the Trainer is certified for the		
, ELE/Q0123, version 3.0". Minimum accepted score is 80%.	Package Design Engineer (Semiconductor) "Trainer (VET and Skills)", mapped to the		
	Qualification Pack: "MEP/Q2601, V2.0", with		
	minimum score of 80%		





### **Assessor Requirements**

	Assessor Prerequisites							
Minimum Educational	Specialization	Relevant Industry Experience		Training/Assessment Experience		Remarks		
Qualification		Years	Specialization	Years	Specialization			
Diploma/ Degree/ ITI/ Certified in relevant CITS Trade	(Electrical/Electronics / Mechanical)	3	Electronic Designing	1	Electronics			

Assessor Certification				
Domain Certification	Platform Certification			
"Package Design Engineer (Semiconductor) , ELE/Q0123, version 3.0". Minimum accepted	Recommended that the Assessor is certified for the Package Design Engineer(Semiconductor)			
score is 80%.	"Assessor (VET and Skills)", mapped to the Qualification Pack: "MEP/Q2701, V2.0", with minimum score of 80%			





#### **Assessment Strategy**

- 1. Assessment System Overview:
  - Batches assigned to the assessment agencies for conducting the assessment on SDMS/SIP or email
  - Assessment agencies send the assessment confirmation to VTP/TC looping SSC
  - The assessment agency deploys the ToA certified Assessor for executing the assessment
  - SSC monitors the assessment process & records
- 2. Testing Environment

To ensure a conducive environment for conducting a test, the trainer will:

- Confirm that the centre is available at the same address as mentioned on SDMS or SIP
- Check the duration of the training.
- Check the Assessment Start and End time to be 10 a.m. and 5 p.m. respectively
- Ensure there are 2 Assessors if the batch size is more than 30.
- Check that the allotted time to the candidates to complete Theory & Practical Assessment is correct.
- Check the mode of assessment—Online (TAB/Computer) or Offline (OMR/PP).
- Confirm the number of TABs on the ground are correct to execute the Assessment smoothly.
- Check the availability of the Lab Equipment for the particular Job Role.
- 3. Assessment Quality Assurance levels / Framework:
  - Question papers created by the Subject Matter Experts (SME)
  - Question papers created by the SME verified by the other subject Matter Experts
  - Questions are mapped with NOS and PC
  - Question papers are prepared considering that level 1 to 3 are for the unskilled & semiskilled individuals, and level 4 and above are for the skilled, supervisor & higher management
  - The assessor must be ToA certified and the trainer must be ToT Certified
  - The assessment agency must follow the assessment guidelines to conduct the assessment
- 4. Types of evidence or evidence-gathering protocol:
  - Time-stamped & geotagged reporting of the assessor from assessment location
  - Centre photographs with signboards and scheme-specific branding
  - Biometric or manual attendance sheet (stamped by TP) of the trainees during the training period
  - Time-stamped & geotagged assessment (Theory + Viva + Practical) photographs & videos
- 5. Method of verification or validation:

To verify the details submitted by the training centre, the assessor will undertake:

- A surprise visit to the assessment location
- A random audit of the batch
- A random audit of any candidate
- 6. Method for assessment documentation, archiving, and access

To protect the assessment papers and information, the assessor will ensure:

• Hard copies of the documents are stored





- Soft copies of the documents & photographs of the assessment are uploaded / accessed from Cloud Storage
- Soft copies of the documents & photographs of the assessment are stored on the Hard drive



## References



#### Glossary

Term	Description
Declarative knowledge	Declarative knowledge refers to facts, concepts and principles that need to be known and/or understood in order to accomplish a task or to solve a problem.
Key Learning	Key learning outcome is the statement of what a learner needs to know, understand and be able to do in order to achieve the terminal outcomes. A set of key learning outcomes will make up the training outcomes. Training outcome is specified in terms of knowledge, understanding (theory) and skills (practical application).
(M) TLO	On-the-job training (Mandatory); trainees are mandated to complete specified hours of training on site
OJT (R)	On-the-job training (Recommended); trainees are recommended the specified hours of training on site
Procedural Knowledge	Procedural knowledge addresses how to do something, or how to perform a
Training Outcome	Training outcome is a statement of what a learner will know, understand and be able to do <b>upon the completion of the training</b> .
Terminal Outcome	Terminal outcome is a statement of what a learner will know, understand and be able to do <b>upon the completion of a module.</b> A set of terminal outcomes help to achieve the training outcome.





## Acronyms and Abbreviations

Term	Description
DC	Direct Current
ISO	International Organization for Standardization
NCO	National Occupational Standards
NOS	National Skills Qualification Committee
NSQF	National Skills Qualification Framework
TLO	On-the-Job Training
OMR	Optical Mark Recognition
РС	Performance Criteria
PwD	Persons with Disabilities
QP	Qualification Pack
SDMS	Skill Development & Management System
SIP	Skill India Portal
SME	Small and Medium Enterprises
SOP	Standard Operating Procedure
SSC	Sector Skill Council
тс	Trainer Certificate
ТоА	Training of Assessors
ТоТ	Training of Trainers
ТР	Training Provider